

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ0902NS	**Issued**	14. August 2015
MA#	MA001015218		
Package	PG-TSDSON-8-26	**Weight***	36.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.393	1.08	1.08	10761	10761
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		270	
	non noble metal	iron	7439-89-6	0.197	0.54		5393	
	non noble metal	copper	7440-50-8	7.988	21.90	22.48	218990	224720
wire	noble metal	gold	7440-57-5	0.030	0.08	0.08	810	810
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1024	
	plastics	epoxy resin	-	1.924	5.28		52751	
	inorganic material	silicondioxide	60676-86-0	16.721	45.84	51.22	458371	512146
leadfinish	non noble metal	tin	7440-31-5	0.400	1.10	1.10	10971	10971
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	557	557
solder	noble metal	silver	7440-22-4	0.016	0.04		425	
	non noble metal	tin	7440-31-5	0.012	0.03		340	
	non noble metal	lead	7439-92-1	0.592	1.62	1.69	16239	17004
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		129	
	non noble metal	iron	7439-89-6	0.094	0.26		2576	
	non noble metal	copper	7440-50-8	3.816	10.46	10.73	104608	107345
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		35	
	non noble metal	zinc	7440-66-6	0.005	0.01		139	
	non noble metal	iron	7439-89-6	0.101	0.28		2776	
	non noble metal	copper	7440-50-8	4.112	11.27	11.56	112736	115686
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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